

Abstract of the Disclosure:

A device having a semiconductor component and a printed circuit board are described. The semiconductor component has external contacts and the printed circuit board has contact  
5 terminals. The contact terminals display a central blind opening, into which the external contacts of the semiconductor component protrude and are in a force-locking engagement with the contact terminal areas. In the method of electromechanically connecting the two parts to form a device,  
10 after they have been aligned, the two components are merely pressed onto each other.

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